

REMARKS

At the outset, the Examiner is thanked for the thorough review and consideration of the pending application. The Office Action dated February 7, 2006, has been received and its contents carefully reviewed.

Applicants amend claims 3, 6, and 13 to overcome the Examiner's objections and the 35 U.S.C. §112 rejection. Claims 3-7 and 10-14 are pending.

In the Office Action, claims 3, 6, 7, 10, 13 and 14 are rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 6,0783,65 to Ueda et al. Claims 4 and 11 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Ueda in view of U.S. Patent No. 6,958,788 to Choi. Claims 5 and 12 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Ueda in view of Choi and in view of U.S. Patent No. 4,855,806 to Parks et al.

The rejection of claims 3-7 is respectfully traversed and reconsideration is requested. Claims 3-7 are allowable over the cited references in that each of these claims recites a combination of elements including, for example, "forming using a third mask process a pixel electrode connected to the drain electrode and the storage electrode, a gate pad protection electrode formed to cover the gate pad, a transparent electrode pattern including the data pad protection electrode formed to cover the data pad, and a gate insulation pattern and a protection film pattern stacked in the a region other than the region where the transparent electrode pattern is formed". None of the cited references including Ueda, Choi, and Parks, singly or in combination, teaches or suggests at least this feature of the claimed invention. The structure of claim 3 of the present invention is different from the Ueda structure in that Ueda does not disclose or suggest "forming using a third mask process...a gate insulation pattern and a protection film pattern stacked in the a region other than the region where the transparent

electrode pattern is formed” as recited in claim 3. Ueda does not disclose or suggest forming all of the structural elements recited in this particular step of claim 3 using a “third mask process”. Neither Choi nor Parks supply this deficiency in Ueda with respect to claim 3. Accordingly, Applicant respectfully submits that claim 3 and claims 4-7, which depend from claim 3, are allowable over the cited references.

The rejection of claims 10-14 is respectfully traversed and reconsideration is requested. Claims 10-14 are allowable over the cited references in that each of these claims recites a combination of elements including, for example, “forming a pixel electrode using a third mask process connected to the drain electrode and the storage electrode, a gate pad protection electrode formed to cover the gate pad, a transparent electrode, a data pad protection electrode covering the data pad, and a gate insulation pattern and a protection film pattern stacked in the a region other than the region where the transparent electrode is formed”. None of the cited references including Ueda, Choi, and Parks, singly or in combination, teaches or suggests at least this feature of the claimed invention. The structure of claim 10 of the present invention is different from the Ueda structure in that Ueda does not disclose or suggest “forming...using a third mask process... a gate insulation pattern and a protection film pattern stacked in the a region other than the region where the transparent electrode is formed” as recited in claim 10. For example, Ueda does not disclose or suggest forming all of the structural elements recited in this particular step of claim 10 using a “third mask process”. Neither Choi nor Parks supply this deficiency in Ueda with respect to claim 10. Accordingly, Applicant respectfully submits that claim 10 and claims 11-14, which depend from claim 10, are allowable over the cited references.

Applicants believe the foregoing amendments and discussion place the application in condition for allowance and early, favorable action is respectfully solicited.

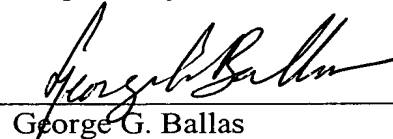
If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is requested to call the undersigned attorney at (202) 496-7500 to discuss the steps necessary for placing the application in condition for allowance. All correspondence should continue to be sent to the below-listed address.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. § 1.136, and any additional fees required under 37 C.F.R. § 1.136 for any necessary extension of time, or any other fees required to complete the filing of this response, may be charged to Deposit Account No. 50-0911. Please credit any overpayment to deposit Account No. 50-0911. *A duplicate copy of this sheet is enclosed.*

Respectfully submitted,

Dated: May 8, 2006

By



George G. Ballas
Registration No. 52,587
McKENNA LONG & ALDRIDGE LLP
1900 K Street, N.W.
Washington, DC 20006
(202) 496-7500
Attorneys for Applicant